	Material Composit © Copyright 2005. IPC, I international and Pan-An	Bannockbi	urn, Illinois. A	Il rights reserved nations.	under both	This docum level parts,	ent is a decla the declaratio	ration of n encom	f the substances	s within the manufactu er level materials for v	urer listed which the u	item. Note: i nanufacture	if the item is an as r has engineering	ssembly with lower responsibility.	
					Form Type Distribute	Form Type * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mate					tials and Mfg Information				
Supplier Informat	tion														
Company name*			Company unique ID			Unique ID Authority					Response Date*				
onsemi										2023-00	2023-06-08				
Contact Name			Title - Contact				Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			Phone - Representative*			Email -	Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com				
Requester I	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective D	ate Ve	ersion	Manufacturing Site		Weight*	UOM	Unit Type	
		NCV1117ST20T3G		1.0A, 2.5V, LDO REGULATOR		R	2023-06-08			MY1		108.86	mg	Each	
Manufacturing Pr	roccess Information	I													
Terminal Plating / Grid Array Material Term			erminal Base A	ninal Base Alloy J-STD-020 MSL F		L Rating	Peak Process Body Temperature Max		are Max Time at Peal	k Tempera	ture Numb	ber of Reflow Cy	cles		
Matte Tin (Sn) - annealed CU Alloy			U Alloy		1		260		С	30	seco	nds 3			
Comments															
level 1 - maximum tim	e at peak temperature d	uring sole	dering is 10-3	0 seconds											
For more information	regarding material com	position p	olease refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	S Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl alate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.1	mg	Supplier	Silicon (Si)	7440-21-3		1.1	mg
Die Attach	0.74	mg		Epoxy resin	proprietary data		0.0185	mg
			Supplier	Silver (Ag)	7440-22-4		0.6253	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0185	mg
			Supplier	Inorganic filler	Proprietary Data		0.0185	mg
			Supplier	Dicyandiamine	461-58-5		0.0037	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.0555	mg
Lead Frame	37.17	mg	Supplier	Silver (Ag)	7440-22-4		0.4832	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0372	mg
			Supplier	Iron (Fe)	7439-89-6		0.8921	mg
			Supplier	Copper (Cu)	7440-50-8		35.7575	mg
Mold Compound-Black	62.4	mg		Epoxy resin	proprietary data		3.12	mg
			Supplier	Phenolic Resin	Proprietary Data		3.12	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.248	mg
			Supplier	Carbon Black (C)	1333-86-4		0.312	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		54.6	mg
Plating	7.44	mg	Supplier	Tin (Sn)	7440-31-5		7.44	mg
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg